



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

3000 Lakeside Dr.
Bannockburn, IL 60015

IPC-TM-650 TEST METHODS MANUAL

2.6.1G Fungus Resistance Printed Wiring Materials

2.6.1.1 Fungus Resistance, Conformance Coating

2.6.2C Moisture Absorption, Flexible Printed Wiring

2.6.2.1A Water Absorption, Metal Clad Plastic Laminates

2.6.3F Moisture and Insulation Resistance, Printed Boards

2.6.3.1E Solder Mask - Moisture and Insulation Resistance

2.6.3.2B Insulation and Moisture Resistance, Flexible Base Dielectric

2.6.3.3B Surface Insulation Resistance, Fluxes

2.6.3.4A Moisture and Insulation Resistance, Conformal Coating

2.6.3.5 Bare Board Cleanliness by Surface Insulation Resistance

2.6.3.6 Surface Insulation Resistance - Fluxes - Telecommunications

2.6.3.7 Surface Insulation Resistance

2.6.4B Outgassing, Printed Boards

2.6.5D Physical Shock, Multilayer Printed Wiring

2.6.6B Temperature Cycling, Printed Wiring Board

2.6.7A Thermal Shock and Continuity, Printed Board

2.6.7.1A Thermal Shock, Conformal Coatings

2.6.7.2B Thermal Shock, Continuity and Microsection, Printed Board

2.6.7.3 Thermal Shock, Solder Mask

2.6.8E Thermal Stress, Plated-Through Holes

Number 2.6	
Subject Environmental Test Methods	
Date 03/07	Revision Y
Originating Task Group	

2.6.8.1 Thermal Stress, Laminate

2.6.9B Vibration, Rigid Printed Wiring

2.6.9.1 Test to Determine Sensitivity of Electronic Assemblies to Ultrasonic Energy

2.6.9.2 Test to Determine Sensitivity of Electronic Components to Ultrasonic Energy

2.6.10A X-Ray (Radiography), Multilayer Printed Wiring

2.6.11D Solder Mask - Hydrolytic Stability

2.6.11.1 Hydrolytic Stability, Conformal Coating

2.6.12 Temperature Testing, Flexible Flat Cable

2.6.13 Withdrawn 09/00; superseded by 2.6.14.1

2.6.14D Solder Mask - Resistance to Electrochemical Migration

2.6.14.1 Electrochemical Migration Resistance Test

2.6.15C Corrosion, Flux

2.6.16 Pressure Vessel Method for Glass Epoxy Laminate Integrity

2.6.16.1 Moisture Resistance of High Density Interconnection (HDI) Materials Under High Temperature and Pressure (Pressure Vessel)

2.6.17 Hydrolytic Stability, Flexible Printed Wiring

2.6.18A Low Temperature Flexibility, Flexible Printed Wiring Materials

2.6.19 Environmental and Insulation Resistance Test of Hybrid Ceramic Multilayer Substrate Boards

Material in this Test Methods Manual was voluntarily established by Technical Committees of IPC. This material is advisory only and its use or adaptation is entirely voluntary. IPC disclaims all liability of any kind as to the use, application, or adaptation of this material. Users are also wholly responsible for protecting themselves against all claims or liabilities for patent infringement.

Copyright IPC-Association Connecting Electronics Industries
Provided by IHS under license with IPC
No reproduction or networking permitted without license from IHS

Full document details: IPC TM-650 2.6 2007

Licensee=Sandia National Lab/5932237100, User=sam, albert
Not for Resale, 05/28/2014 10:55:26 MDT



Documents
Page 1 of 2
Document Sharing Hub

IPC-TM-650		
Number 2.6	Subject Environmental Test Methods	Date 03/07
Revision Y		

2.6.20A Superseded by J-STD-020A

2.6.21 Service Temperature of Flexible Printed Wiring

2.6.22 Withdrawn 10/98; superseded by J-STD-035

2.6.23 Test Procedure for Steam Ager Temperature Repeatability

2.6.24 Junction Stability Under Environmental Conditions

2.6.25 Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis

2.6.26 DC Current Induced Thermal Cycling Test